

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Hau-Wei Wang</td><td>08/17/2006</td></tr><tr><td>Fu-Shiang Yang</td><td>08/10/2006</td></tr><tr><td>Ding-Hsiang Pan</td><td>08/14/2006</td></tr></tbody></table>	Name	Execution Date	Hau-Wei Wang	08/17/2006	Fu-Shiang Yang	08/10/2006	Ding-Hsiang Pan	08/14/2006	
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Hau-Wei Wang	08/17/2006								
Fu-Shiang Yang	08/10/2006								
Ding-Hsiang Pan	08/14/2006								
RECEIVING PARTY DATA									
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Street Address:	No. 195, Section 4, Chung Hsing Road, Chutung								
City:	Hsinchu								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11469904</td></tr></tbody></table>	Property Type	Number	Application Number:	11469904					
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Application Number:	11469904								
CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	Belinda Lee								
Total Attachments: 2 source=18643-ASSIGNMENT#page1.tif source=18643-ASSIGNMENT#page2.tif									

CH 11469904 \$40.00

ASSIGNMENT

WHEREAS,

1. Hau-Wei Wang
3. Ding-Hsiang Pan

2. Fu-Shiang Yang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **HIGH-DENSITY CHANNELS DETECTING DEVICE**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Section 4, Chung Hsing Road, Chutung, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Hau-Wei Wang
Sole or First Joint Inventor: Hau-Wei Wang

Date: 2006. 8/17

Signature: Fu-Shiang Yang
Second Joint Inventor (if any): Fu-Shiang Yang

Date: 2006. 8/10

Signature: Ding-Hsiang Pan
Third Joint Inventor (if any): Ding-Hsiang Pan

Date: 2006. 8/14